# Low-Voltage 1.8/2.5/3.3V 16-Bit D-Type Flip-Flop With 3.6V–Tolerant Inputs and Outputs (3–State, Non–Inverting)

The NL74VCXH16374 is an advanced performance, non-inverting 16-bit D-type flip-flop. It is designed for very high-speed, very low-power operation in 1.8V, 2.5V or 3.3V systems. The VCX16374 is byte controlled, with each byte functioning identically, but independently. Each byte has separate Output Enable and Clock Pulse inputs. These control pins can be tied together for full 16-bit operation.

When operating at 2.5V (or 1.8V) the part is designed to tolerate voltages it may encounter on either inputs or outputs when interfacing to 3.3V busses. It is guaranteed to be over-voltage tolerant to 3.6V.

The NL74VCXH16374 consists of 16 edge–triggered flip–flops with individual D–type inputs and 3.6V–tolerant 3–state outputs. The clocks (CPn) and Output Enables ( $\overline{OEn}$ ) are common to all flip–flops within the respective byte. The flip–flops will store the state of individual D inputs that meet the setup and hold time requirements on the LOW–to–HIGH Clock (CP) transition. With the  $\overline{OE}$  LOW, the contents of the flip–flops are available at the outputs. When the  $\overline{OE}$  is HIGH, the outputs go to the high impedance state. The  $\overline{OE}$  input level does not affect the operation of the flip–flops. The data inputs include active bushold circuitry, eliminating the need for external pull–up resistors to hold unused or floating inputs at a valid logic state.

- Designed for Low Voltage Operation:  $V_{CC} = 1.65 3.6V$
- 3.6V Tolerant Inputs and Outputs
- High Speed Operation: 3.0ns max for 3.0 to 3.6V

3.9ns max for 2.3 to 2.7V 7.8ns max for 1.65 to 1.95V

- Static Drive: ±24mA Drive at 3.0V ±18mA Drive at 2.3V ±6mA Drive at 1.65V
- Supports Live Insertion and Withdrawal
- Includes Active Bushold to Hold Unused or Floating Inputs at a Valid Logic State
- IOFF Specification Guarantees High Impedance When  $V_{CC} = 0V^{\dagger}$
- Near Zero Static Supply Current in All Three Logic States (20µA) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds ±300mA @ 125°C
- ESD Performance: Human Body Model >2000V; Machine Model >200V
- **†NOTE:** To ensure the outputs activate in the 3–state condition, the output enable pins should be connected to V<sub>CC</sub> through a pull–up resistor. The value of the resistor is determined by the current sinking capability of the output connected to the  $\overline{\text{OE}}$  pin.



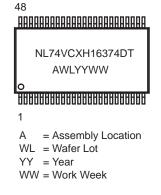
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DT SUFFIX CASE 1201

# MARKING DIAGRAM

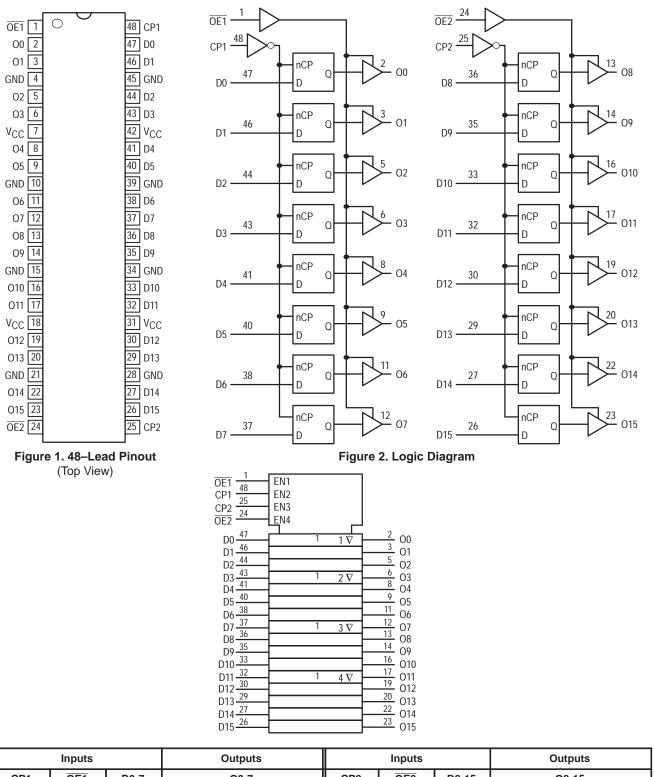


#### PIN NAMES

Pins	Function
OEn CPn	Output Enable Inputs
D0-D15	Clock Pulse Inputs Inputs
00–015	Outputs

#### ORDERING INFORMATION

Device	Package	Shipping
NL74VCXH16374DT	TSSOP	39 / Rail
NL74VCXH16374DTR	TSSOP	2500 / Reel



	inputs		Outputs		inputs		Outputs
CP1	OE1	D0:7	O0:7	CP2	OE2	D8:15	O8:15
↑	L	Н	Н	$\uparrow$	L	Н	Н
↑	L	L	L	↑	L	L	L
Х	L	Х	O0	Х	L	Х	O0
Х	Н	Х	Z	Х	Н	Х	Z

Г

H = High Voltage Level; L = Low Voltage Level; Z = High Impedance State;  $\uparrow$  = Low–to–High Transition; X = High or Low Voltage Level and Transitions Are Acceptable, for I<sub>CC</sub> reasons, DO NOT FLOAT Inputs. O0 = No Change.

#### **ABSOLUTE MAXIMUM RATINGS\***

Symbol	Parameter	Value	Condition	Unit
V <sub>CC</sub>	DC Supply Voltage	-0.5 to +4.6		V
VI	DC Input Voltage	$-0.5 \le V_{I} \le +4.6$		V
VO	DC Output Voltage	$-0.5 \le V_{O} \le +4.6$	Output in 3–State	V
		$-0.5 \le V_O \le V_{CC} + 0.5$	Note 1.; Outputs Active	V
IIК	DC Input Diode Current	-50	V <sub>I</sub> < GND	mA
lok	DC Output Diode Current	-50	V <sub>O</sub> < GND	mA
		+50	VO > ACC	mA
IO	DC Output Source/Sink Current	±50		mA
ICC	DC Supply Current Per Supply Pin	±100		mA
I <sub>GND</sub>	DC Ground Current Per Ground Pin	±100		mA
TSTG	Storage Temperature Range	-65 to +150		°C

\* Absolute maximum continuous ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute-maximum-rated conditions is not implied.

1. IO absolute maximum rating must be observed.

#### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter		Min	Тур	Max	Unit
VCC	Supply Voltage	Operating Data Retention Only	1.65 1.2	3.3 3.3	3.6 3.6	V
VI	Input Voltage		-0.3		3.6	V
VO	Output Voltage	(Active State) (3–State)	0 0		V <sub>CC</sub> 3.6	V
ЮН	HIGH Level Output Current, V <sub>CC</sub> = 3.0V – 3.6V				-24	mA
IOL	LOW Level Output Current, V <sub>CC</sub> = 3.0V – 3.6V				24	mA
IОН	HIGH Level Output Current, V <sub>CC</sub> = 2.3V – 2.7V				-18	mA
IOL	LOW Level Output Current, V <sub>CC</sub> = 2.3V – 2.7V				18	mA
ЮН	HIGH Level Output Current, V <sub>CC</sub> = 1.65 – 1.95V				-6	mA
I <sub>OL</sub>	LOW Level Output Current, V <sub>CC</sub> = 1.65 – 1.95V				6	mA
Т <sub>А</sub>	Operating Free–Air Temperature				+85	°C
$\Delta t / \Delta V$	Input Transition Rise or Fall Rate, $V_{IN}$ from 0.8V to	2.0V, V <sub>CC</sub> = 3.0V	0		10	ns/V

### DC ELECTRICAL CHARACTERISTICS

			T <sub>A</sub> = -40°	C to +85°C	
Symbol	Characteristic	Condition	Min	Max	Uni
VIH	HIGH Level Input Voltage (Note 2.)	1.65V ≤ V <sub>CC</sub> < 2.3V	0.65 x V <sub>CC</sub>		V
		$2.3V \le V_{CC} \le 2.7V$	1.6		
		2.7V < V <sub>CC</sub> ≤ 3.6V	2.0		
VIL	LOW Level Input Voltage (Note 2.)	1.65V ≤ V <sub>CC</sub> < 2.3V		0.35 x V <sub>CC</sub>	V
		$2.3V \le V_{CC} \le 2.7V$		0.7	
		2.7V < V <sub>CC</sub> ≤ 3.6V		0.8	
Vон	HIGH Level Output Voltage	$1.65V \le V_{CC} \le 3.6V; I_{OH} = -100\mu A$	V <sub>CC</sub> - 0.2		V
		V <sub>CC</sub> = 1.65V; I <sub>OH</sub> = -6mA	1.25		
		V <sub>CC</sub> = 2.3V; I <sub>OH</sub> = -6mA	2.0		
		V <sub>CC</sub> = 2.3V; I <sub>OH</sub> = -12mA	1.8		
		V <sub>CC</sub> = 2.3V; I <sub>OH</sub> = -18mA	1.7		
		V <sub>CC</sub> = 2.7V; I <sub>OH</sub> = -12mA	2.2		
		V <sub>CC</sub> = 3.0V; I <sub>OH</sub> = -18mA	2.4		
		V <sub>CC</sub> = 3.0V; I <sub>OH</sub> = -24mA	2.2		
Vol	LOW Level Output Voltage	$1.65V \le V_{CC} \le 3.6V; I_{OL} = 100\mu A$		0.2	V
		V <sub>CC</sub> = 1.65V; I <sub>OL</sub> = 6mA		0.3	
		V <sub>CC</sub> = 2.3V; I <sub>OL</sub> = 12mA		0.4	
		V <sub>CC</sub> = 2.3V; I <sub>OL</sub> = 18mA		0.6	
		V <sub>CC</sub> = 2.7V; I <sub>OL</sub> = 12mA		0.4	
		V <sub>CC</sub> = 3.0V; I <sub>OL</sub> = 18mA		0.4	
		V <sub>CC</sub> = 3.0V; I <sub>OL</sub> = 24mA		0.55	
lı	Input Leakage Current	$1.65V \le V_{CC} \le 3.6V; \ 0V \le V_I \le 3.6V$		±5.0	μA
II(HOLD)	Minimum Bushold Input Current	V <sub>CC</sub> = 3.0V, V <sub>IN</sub> = 0.8V	75		μA
		V <sub>CC</sub> = 3.0V, V <sub>IN</sub> = 2.0V	-75		
		V <sub>CC</sub> = 2.3V, V <sub>IN</sub> = 0.7V	45		
		V <sub>CC</sub> = 2.3V, V <sub>IN</sub> = 1.6V	-45		
		V <sub>CC</sub> = 1.65V, V <sub>IN</sub> = 0.57V	25		
		V <sub>CC</sub> = 1.65V, V <sub>IN</sub> = 1.07V	-25		
II (OD)	Minimum Bushold Over–Drive	V <sub>CC</sub> = 3.6V, (Note 3.)	450		μA
. ,	Current Needed to Change State	V <sub>CC</sub> = 3.6V, (Note 4.)	-450		
		V <sub>CC</sub> = 2.7V, (Note 3.)	300		
		V <sub>CC</sub> = 2.7V, (Note 4.)	-300		
		V <sub>CC</sub> = 1.95V, (Note 3.)	200		
		V <sub>CC</sub> = 1.95V, (Note 4.)	-200		
loz	3–State Output Current	$1.65V \le V_{CC} \le 3.6V; \ 0V \le V_O \le 3.6V;$ $V_I = V_{IH} \text{ or } V_{IL}$		±10	μA
IOFF	Power–Off Leakage Current	$V_{CC} = 0V; V_I \text{ or } V_O = 3.6V$	1	10	μA
ICC	Quiescent Supply Current (Note 5.)	$1.65V \le V_{CC} \le 3.6V$ ; V <sub>I</sub> = GND or V <sub>CC</sub>	1	20	μA
		$1.65V \le V_{CC} \le 3.6V; 3.6V \le V_{I}, V_{O} \le 3.6V$		±20	μA
ΔICC	Increase in I <sub>CC</sub> per Input	$2.7V < V_{CC} \le 3.6V; V_{IH} = V_{CC} - 0.6V$		750	μA

These values of V<sub>I</sub> are used to test DC electrical characteristics only.
An external driver must source at least the specified current to switch from LOW-to-HIGH
An external driver must source at least the specified current to switch from HIGH-to-LOW
Outputs disabled or 3-state only.

## **AC CHARACTERISTICS** (Note 6.; $t_R = t_F = 2.0n_s$ ; $C_L = 30p_F$ ; $R_L = 500\Omega$ )

					Liı	nits			
		T <sub>A</sub> = −40°C to +85°C						1	
			V <sub>CC</sub> = 3.0	0V to 3.6V	V <sub>CC</sub> = 2.3	3V to 2.7V	V <sub>CC</sub> = 1.6	5 to 1.95V	
Symbol	Parameter	Waveform	Min	Max	Min	Max	Min	Max	Unit
f <sub>max</sub>	Clock Pulse Frequency	1	250		200		100		MHz
<sup>t</sup> PLH <sup>t</sup> PHL	Propagation Delay CP to On	1	0.8 0.8	3.0 3.0	1.0 1.0	3.9 3.9	1.5 1.5	7.8 7.8	ns
<sup>t</sup> PZH <sup>t</sup> PZL	Output Enable Time to High and Low Level	2	0.8 0.8	3.5 3.5	1.0 1.0	4.6 4.6	1.5 1.5	9.2 9.2	ns
<sup>t</sup> PHZ tPLZ	Output Disable Time From High and Low Level	2	0.8 0.8	3.5 3.5	1.0 1.0	3.8 3.8	1.5 1.5	6.8 6.8	ns
t <sub>S</sub>	Setup Time, High or Low Dn to CP	3	1.5		1.5		2.5		ns
t <sub>h</sub>	Hold Time, High or Low Dn to CP	3	1.0		1.0		1.0		ns
t <sub>W</sub>	CP Pulse Width, High	3	1.5		1.5		4.0		ns
<sup>t</sup> OSHL <sup>t</sup> OSLH	Output-to-Output Skew (Note 7.)			0.5 0.5		0.5 0.5		0.75 0.75	ns

6. For  $C_L = 50 pF$ , add approximately 300ps to the AC maximum specification.

 Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH–to–LOW (t<sub>OSHL</sub>) or LOW–to–HIGH (t<sub>OSLH</sub>); parameter guaranteed by design.

			T <sub>A</sub> = +25°C	
Symbol	Characteristic	Condition	Тур	Unit
VOLP	Dynamic LOW Peak Voltage	$V_{CC} = 1.8V, C_L = 30pF, V_{IH} = V_{CC}, V_{IL} = 0V$	0.25	V
	(Note 8.)	$V_{CC}$ = 2.5V, $C_L$ = 30pF, $V_{IH}$ = $V_{CC}$ , $V_{IL}$ = 0V	0.6	]
		$V_{CC}$ = 3.3V, $C_{L}$ = 30pF, $V_{IH}$ = $V_{CC}$ , $V_{IL}$ = 0V	0.8	
VOLV	Dynamic LOW Valley Voltage	$V_{CC}$ = 1.8V, $C_L$ = 30pF, $V_{IH}$ = $V_{CC}$ , $V_{IL}$ = 0V	-0.25	V
	(Note 8.)	$V_{CC}$ = 2.5V, $C_L$ = 30pF, $V_{IH}$ = $V_{CC}$ , $V_{IL}$ = 0V	-0.6	]
		$V_{CC}$ = 3.3V, $C_L$ = 30pF, $V_{IH}$ = $V_{CC}$ , $V_{IL}$ = 0V	-0.8	
VOHV	Dynamic HIGH Valley Voltage	$V_{CC}$ = 1.8V, $C_L$ = 30pF, $V_{IH}$ = $V_{CC}$ , $V_{IL}$ = 0V	1.5	V
	(Note 9.)	$V_{CC}$ = 2.5V, $C_L$ = 30pF, $V_{IH}$ = $V_{CC}$ , $V_{IL}$ = 0V	1.9	]
		$V_{CC}$ = 3.3V, $C_{L}$ = 30pF, $V_{IH}$ = $V_{CC}$ , $V_{IL}$ = 0V	2.2	

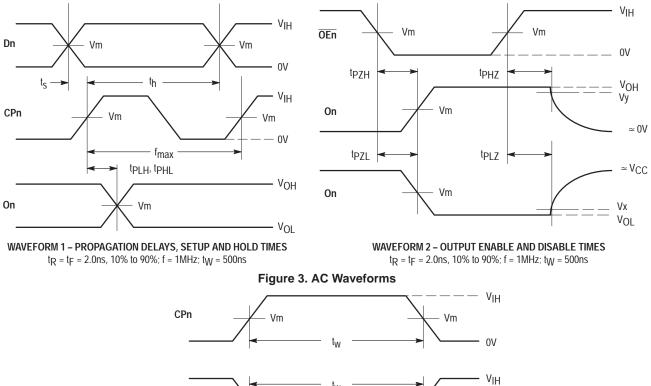
8. Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

9. Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the HIGH state.

#### **CAPACITIVE CHARACTERISTICS**

Symbol	Parameter	Condition	Typical	Unit
CIN	Input Capacitance	Note 10.	6	pF
COUT	Output Capacitance	Note 10.	7	pF
C <sub>PD</sub>	Power Dissipation Capacitance	Note 10., 10MHz	20	pF

10.  $V_{CC}$  = 1.8, 2.5 or 3.3V;  $V_{I}$  = 0V or  $V_{CC}$ .

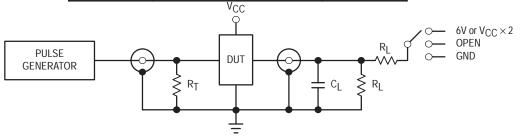




WAVEFORM 3 - PULSE WIDTH  $t_R = t_F = 2.0$ ns (or fast as required) from 10% to 90%

# Figure 4. AC Waveforms

	Vcc				
Symbol	3.3V ±0.3V	2.5V ±0.2V	1.8V ±0.15V		
VIH	2.7V	VCC	Vcc		
Vm	1.5V	V <sub>CC</sub> /2	V <sub>CC</sub> /2		
V <sub>X</sub>	V <sub>OL</sub> + 0.3V	V <sub>OL</sub> + 0.15V	V <sub>OL</sub> + 0.15V		
Vy	V <sub>OH</sub> – 0.3V	V <sub>OH</sub> – 0.15V	V <sub>OH</sub> – 0.15V		

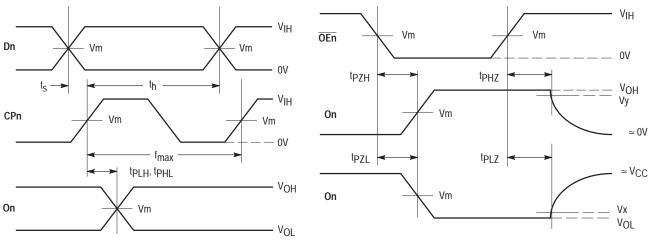


TEST	SWITCH
tPLH, tPHL	Open
tPZL, tPLZ	6V at V <sub>CC</sub> = 3.3 ±0.3V; V <sub>CC</sub> × 2 at V <sub>CC</sub> = 2.5 ±0.2V; 1.8V ±0.15V
<sup>t</sup> PZH <sup>, t</sup> PHZ	GND

 $C_L$  = 30pF or equivalent (Includes jig and probe capacitance)

 $R_{L} = 500\Omega$  or equivalent

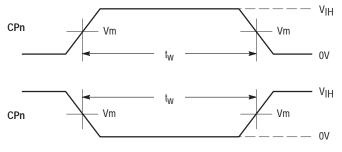
 $R_T = Z_{OUT}$  of pulse generator (typically 50 $\Omega$ ) Figure 5. Test Circuit





WAVEFORM 5 – OUTPUT ENABLE AND DISABLE TIMES  $t_R = t_F = 2.0ns$ , 10% to 90%; f = 1MHz;  $t_W = 500ns$ 





$$\label{eq:WAVEFORM 6-PULSE WIDTH} \begin{split} & \textbf{WAVEFORM 6-PULSE WIDTH} \\ & \textbf{t}_R = \textbf{t}_F = 2.0 ns \text{ (or fast as required) from 10\% to 90\%} \end{split}$$

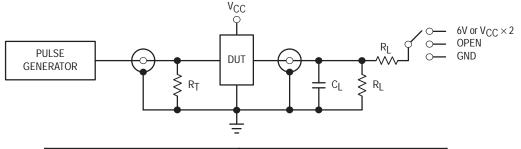
Figure 7. AC Waveforms

	V <sub>CC</sub>			
Symbol	3.3V ±0.3V	2.7V		
VIH	2.7V	2.7V		
Vm	1.5V	1.5V		
V <sub>X</sub>	V <sub>OL</sub> + 0.3V	V <sub>OL</sub> + 0.3V		
Vy	V <sub>OH</sub> – 0.3V	V <sub>OH</sub> – 0.3V		

## AC CHARACTERISTICS ( $t_R = t_F = 2.0ns$ ; $C_L = 50pF$ ; $R_L = 500\Omega$ )

				-			
			T <sub>A</sub> = −40°C to +85°C				
			V <sub>CC</sub> = 3.0V to 3.6V		V <sub>CC</sub> = 2.7V		1
Symbol	Parameter	Waveform	Min	Max	Min	Max	Unit
f <sub>max</sub>	Clock Pulse Frequency	4	150		150		MHz
<sup>t</sup> PLH <sup>t</sup> PHL	Propagation Delay CP to On	4	1.0 1.0	4.2 4.2		4.9 4.9	ns
<sup>t</sup> PZH <sup>t</sup> PZL	Output Enable Time to High and Low Level	5	1.0 1.0	4.8 4.8		5.9 5.9	ns
<sup>t</sup> PHZ <sup>t</sup> PLZ	Output Disable Time From High and Low Level	5	1.0 1.0	4.3 4.3		4.7 4.7	ns
<sup>t</sup> OSHL <sup>t</sup> OSLH	Output–to–Output Skew (Note 11.)			0.5 0.5		0.5 0.5	ns

11. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (toSHL) or LOW-to-HIGH (toSLH); parameter guaranteed by design.

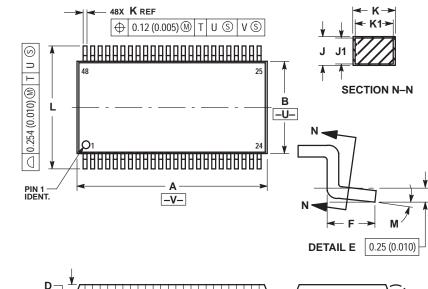


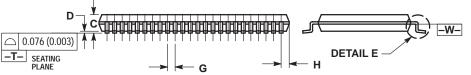
TEST	SWITCH
<sup>t</sup> PLH <sup>, t</sup> PHL	Open
<sup>t</sup> PZL, <sup>t</sup> PLZ	6V at V <sub>CC</sub> = $3.3 \pm 0.3$ V; V <sub>CC</sub> ×2 at V <sub>CC</sub> = $2.5 \pm 0.2$ V; $1.8$ V $\pm 0.15$ V
<sup>t</sup> PZH <sup>, t</sup> PHZ	GND

 $C_L = 50 pF$  or equivalent (Includes jig and probe capacitance)  $R_L = 500\Omega$  or equivalent  $R_T = Z_{OUT}$  of pulse generator (typically 50 $\Omega$ ) **Figure 8. Test Circuit** 

## PACKAGE DIMENSIONS

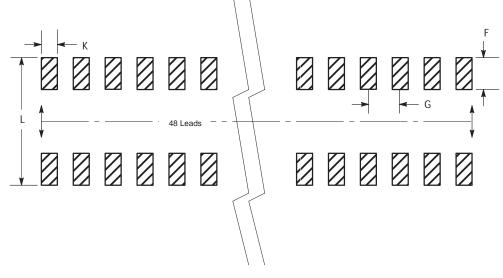
TSSOP **DT SUFFIX** CASE 1201-01 **ISSUE A** 



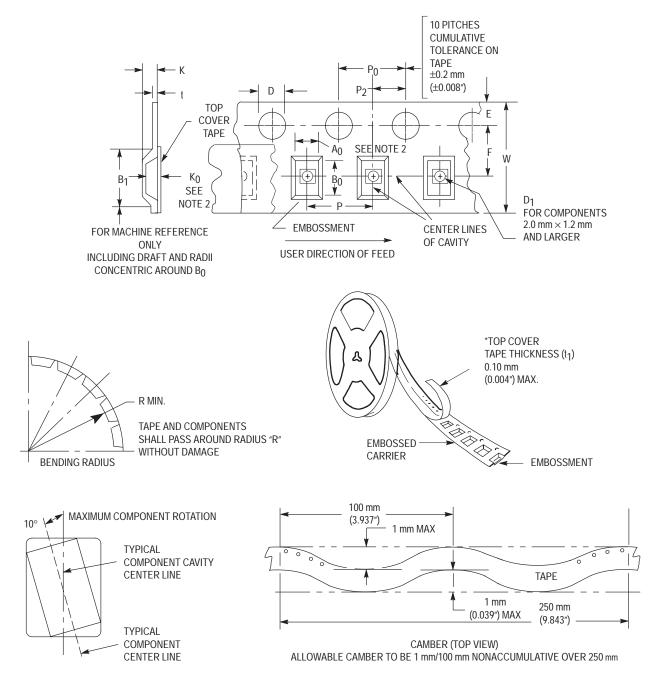


- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER. 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (# 0004) DED SHE SHALL NOT EXCEED 0.15 (0.006) PER SIDE. 4. DIMENSION K DOES NOT INCLUDE DAMBAR
- PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
- 5. TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY. DIMENSIONS A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-. 6.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	12.40	12.60	0.488	0.496	
В	6.00	6.20	0.236	0.244	
С		1.10		0.043	
D	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.50 BSC		0.0197 BSC		
Н	0.37		0.015		
J	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
K	0.17	0.27	0.007	0.011	
K1	0.17	0.23	0.007	0.009	
L	7.95	8.25	0.313	0.325	
Μ	0 °	8 °	0 °	8 °	



Package Footprint





Tape Size	B <sub>1</sub> Max	D	D <sub>1</sub>	E	F	К	Р	P <sub>0</sub>	P <sub>2</sub>	R	т	w
24mm	20.1mm (0.791″)	1.5 + 0.1mm -0.0 (0.059 +0.004" -0.0)	1.5mm Min (0.060″)	1.75 ±0.1 mm (0.069 ±0.004")	11.5 ±0.10 mm (0.453 ±0.004")	11.9 mm Max (0.468")	16.0 ±0.1 mm (0.63 ±0.004")	4.0 ±0.1 mm (0.157 ±0.004")	2.0 ±0.1 mm (0.079 ±0.004")	30 mm (1.18″)	0.6 mm (0.024")	24.3 mm (0.957")

EMBOSSED CARRIER DIMENSIONS	(See Notes 1 and 2)
	(0cc notes i and z)

1. Metric Dimensions Govern–English are in parentheses for reference only.

 A<sub>0</sub>, B<sub>0</sub>, and K<sub>0</sub> are determined by component size. The clearance between the components and the cavity must be within 0.05 mm min to 0.50 mm max. The component cannot rotate more than 10° within the determined cavity

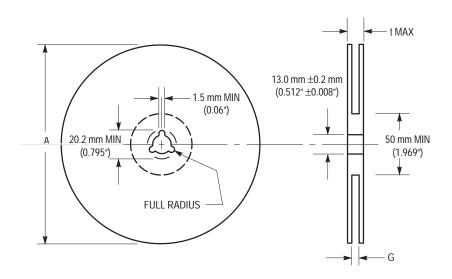
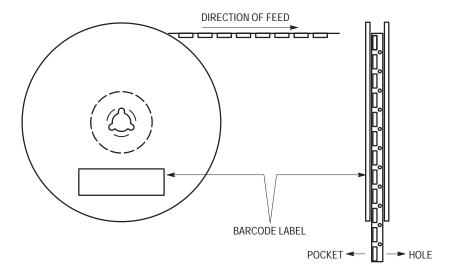


Figure 10. Reel Dimensions

#### **REEL DIMENSIONS**

Tape Size	A Max	G	t Max
24 mm	360 mm	24.4 mm + 2.0 mm, -0.0	30.4 mm
	(14.173")	(0.961" + 0.078", -0.00)	(1.197″)





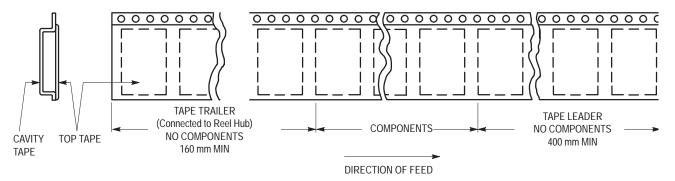


Figure 12. Tape Ends for Finished Goods

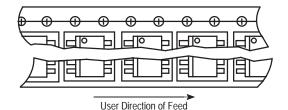


Figure 13. Reel Configuration

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